



QNHCHIP

QNM20PD02AJ

Product Specification

QNM20PD02AJ

20V Dual P-Channel MOSFET



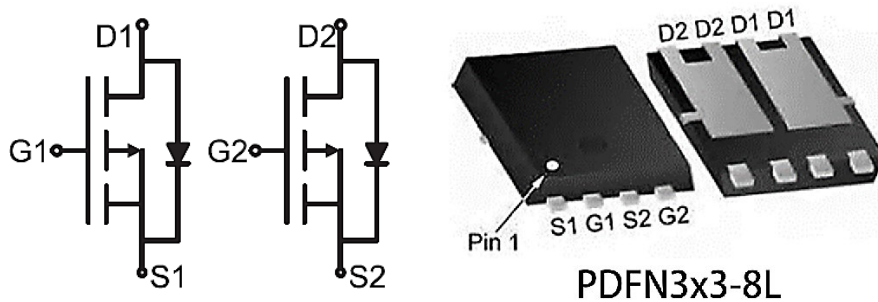
FEATURES

- -20V, -20A
 $R_{DS(ON)}=12.5\text{ m}\Omega @ V_{GS}=-4.5\text{V(Typ.)}$
 $R_{DS(ON)}=16.5\text{ m}\Omega @ V_{GS}=-2.5\text{V(Typ.)}$
- Advanced Trench Technology
- Provide Excellent $R_{DS(ON)}$ and Low Gate Charge
- Lead free product is acquired

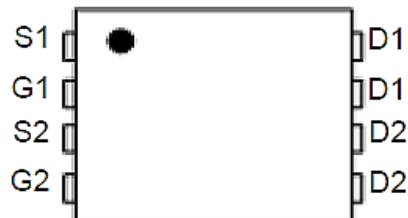
Applications

- Load Switch
- PWM Application
- Power management

Pin Description



Top View



| NO. | Symbol | Description |
|-----|--------|-------------|
| 1 | S1 | SOURCE |
| 2 | G1 | GATE |
| 3 | S2 | SOURCE |
| 4 | G2 | GATE |
| 5 | D1 | DRAIN |
| 6 | D1 | DRAIN |
| 7 | D2 | DRAIN |
| 8 | D2 | DRAIN |



Absolute Maximum Ratings

(@ $T_A = 25^\circ\text{C}$ unless otherwise specified)

| Symbol | Parameter | Limit | Unit |
|-------------------------------|--|------------|---------------------------|
| V_{DS} | Drain-Source Voltage | -20 | V |
| V_{GS} | Gate-Source Voltage | +12 | V |
| I_D | Drain Current -Continuous | -20 | A |
| I_{DM} | Drain Current -Pulsed ⁽¹⁾ | -80 | A |
| P_D | Maximum Power Dissipation | 15 | W |
| T_J, T_{STG} | Operating Junction and Storage Temperature Range | -55 To 150 | $^\circ\text{C}$ |
| Thermal Characteristic | | | |
| $R_{\theta JA}$ | Thermal Resistance, Junction-to-Ambient ⁽²⁾ | 4.5 | $^\circ\text{C}/\text{W}$ |



Electrical Characteristics

(T_J = 25°C unless otherwise specified)

| Symbol | Parameter | Test Condition | Min. | Typ. | Max. | Units |
|---|--|---|------|------|------|-------|
| Off Characteristic | | | | | | |
| V _{(BR)DSS} | Drain-Source Breakdown Voltage | V _{GS} =0V, I _D = -250μA | -20 | - | - | V |
| I _{DSS} | Zero Gate Voltage Drain Current | V _{DS} = -20V, V _{GS} =0V, | - | - | -1 | μA |
| I _{GSS} | Gate to Body Leakage Current | V _{DS} =0V, V _{GS} = ±12V | - | - | ±100 | nA |
| On Characteristics | | | | | | |
| V _{GS(th)} | Gate Threshold Voltage | V _{DS} =V _{GS} , I _D = -250μA | -0.4 | -0.7 | -1.0 | V |
| R _{DS(on)} | Static Drain-Source on-Resistance ⁽³⁾ | V _{GS} = -4.5V, I _D = -10A | - | 12.5 | 15 | mΩ |
| | | V _{GS} = -2.5V, I _D = -5A | - | 16.5 | 20 | |
| Dynamic Characteristics | | | | | | |
| C _{iss} | Input Capacitance | V _{DS} = -10V, V _{GS} =0V, f=1.0MHz | - | 1764 | - | pF |
| C _{oss} | Output Capacitance | | - | 171 | - | pF |
| C _{rss} | Reverse Transfer Capacitance | | - | 143 | - | pF |
| Q _g | Total Gate Charge | V _{DS} = -10V, I _D = -6A, V _{GS} = -4.5V | - | 16 | - | nC |
| Q _{gs} | Gate-Source Charge | | - | 3 | - | nC |
| Q _{gd} | Gate-Drain("Miller") Charge | | - | 4 | - | nC |
| Switching Characteristics | | | | | | |
| t _{d(on)} | Turn-on Delay Time | V _{DD} = -10V, I _D = -12A, V _{GS} = -4.5V, R _{GEN} =2.4Ω | - | 14 | - | ns |
| t _r | Turn-on Rise Time | | - | 79 | - | ns |
| t _{d(off)} | Turn-off Delay Time | | - | 76 | - | ns |
| t _f | Turn-off Fall Time | | - | 76 | - | ns |
| Drain-Source Diode Characteristics and Maximum Ratings | | | | | | |
| I _S | Maximum Continuous Drain to Source Diode Forward Current | | - | - | -20 | A |
| I _{SM} | Maximum Pulsed Drain to Source Diode Forward Current | | - | - | -80 | A |
| V _{SD} | Drain to Source Diode Forward Voltage | V _{GS} =0V, I _S = -20A | - | -0.8 | -1.2 | V |
| t _{rr} | Body Diode Reverse Recovery Time | I _F =-2A, di/dt=- 100A/μs | - | 180 | - | ns |
| Q _{rr} | Body Diode Reverse Recovery Charge | | - | 300 | - | nC |

Notes: 1.Repetitive Rating: Pulse Width Limited by Maximum Junction Temperature

2.EAS condition : T_J=25°C, V_{DD}=-10V, V_G=10V, L=0.5mH, R_g=25 Ω, I_{AS}=-12A

3.Pulse Test: Pulse Width ≤ 300us, Duty Cycle ≤ 2%



Typical Performance Characteristics

Figure 1: Output Characteristics

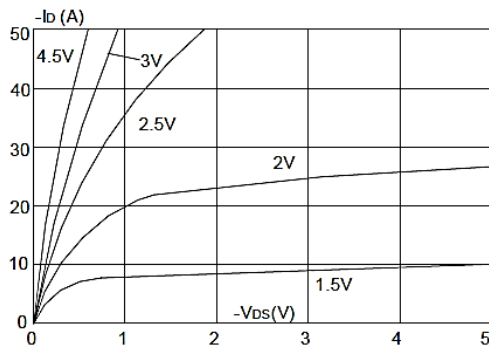


Figure 2: Typical Transfer Characteristics

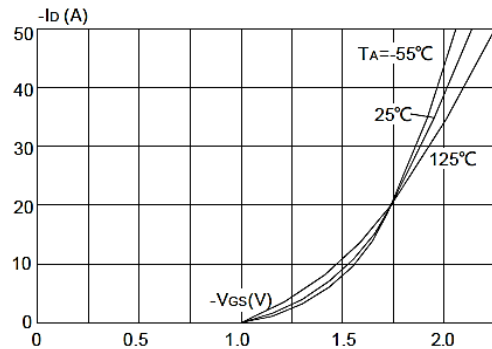


Figure 3: On-resistance vs. Drain Current

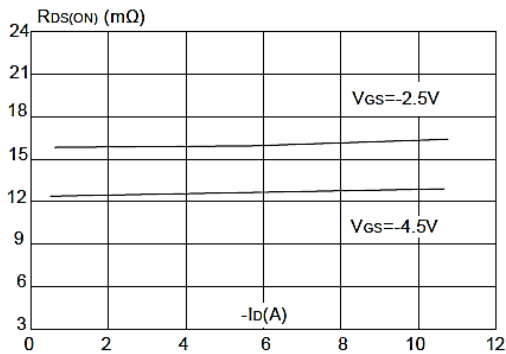


Figure 4: Body Diode Characteristics

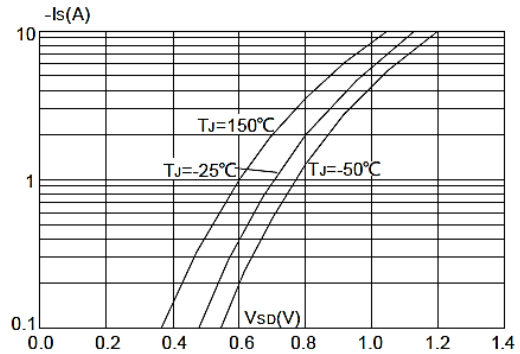


Figure 5: Gate Charge Characteristics

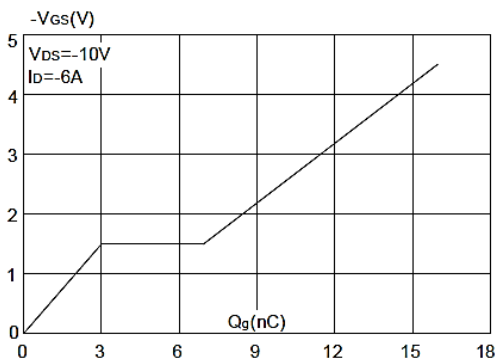


Figure 6: Capacitance Characteristics

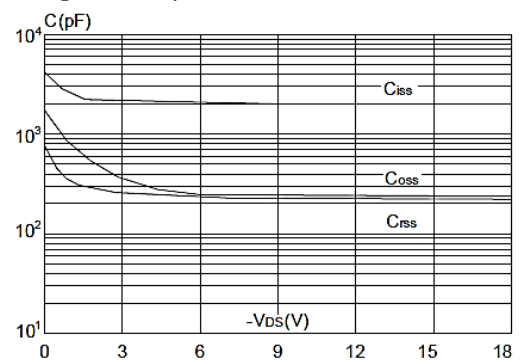


Figure 7: Normalized Breakdown Voltage vs. Junction Temperature

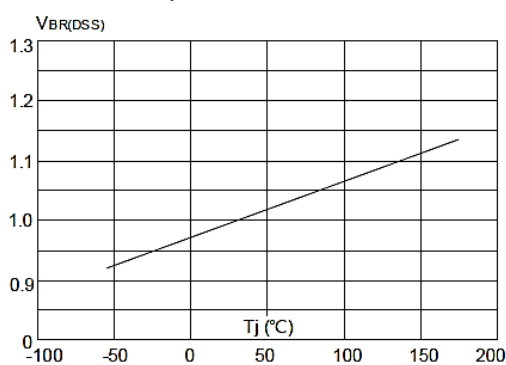


Figure 8: Normalized on Resistance vs. Junction Temperature

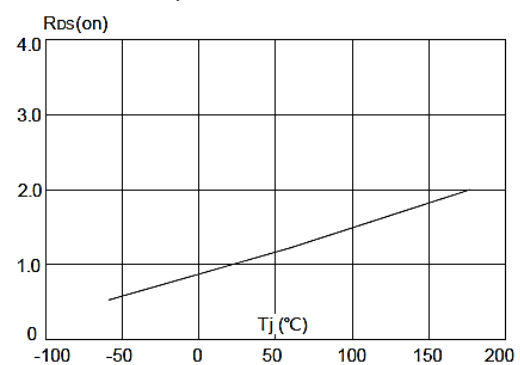




Figure 9: Maximum Safe Operating Area

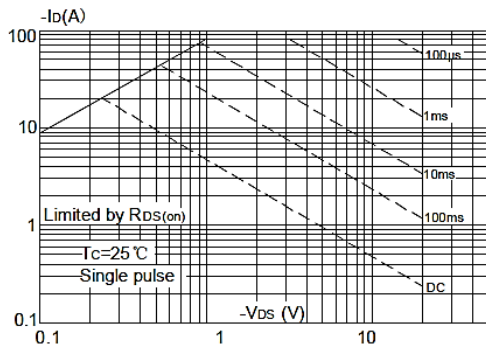


Figure 10: Maximum Continuous Drain Current vs. Case Temperature

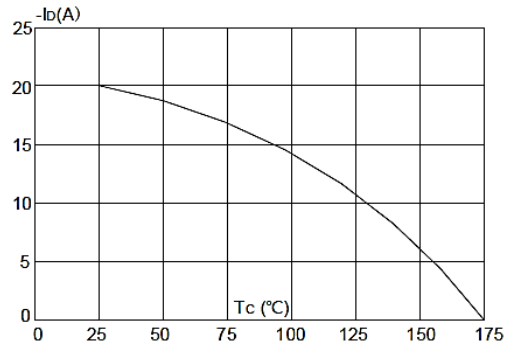
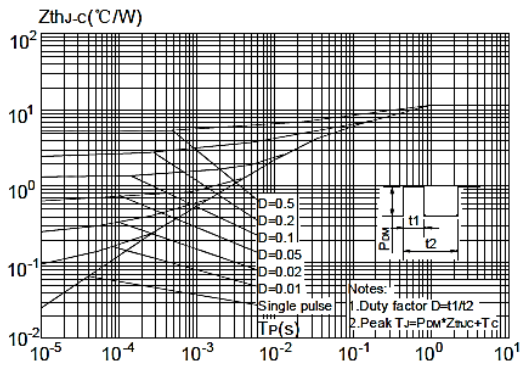


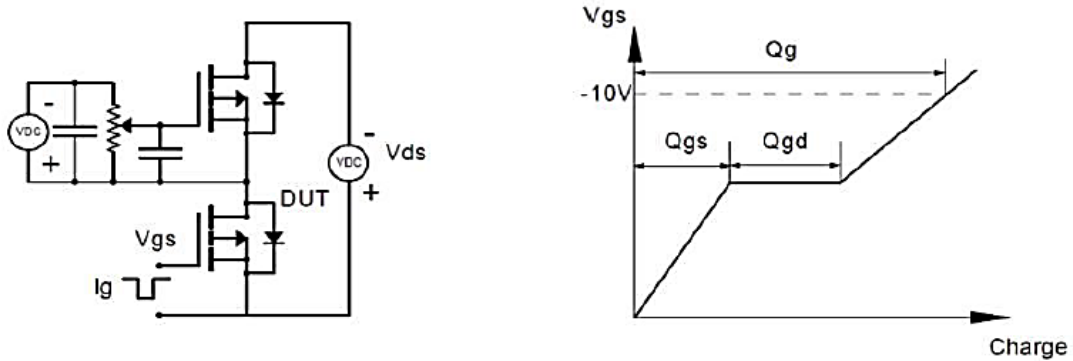
Figure.11: Maximum Effective Transient Thermal Impedance, Junction-to-Case



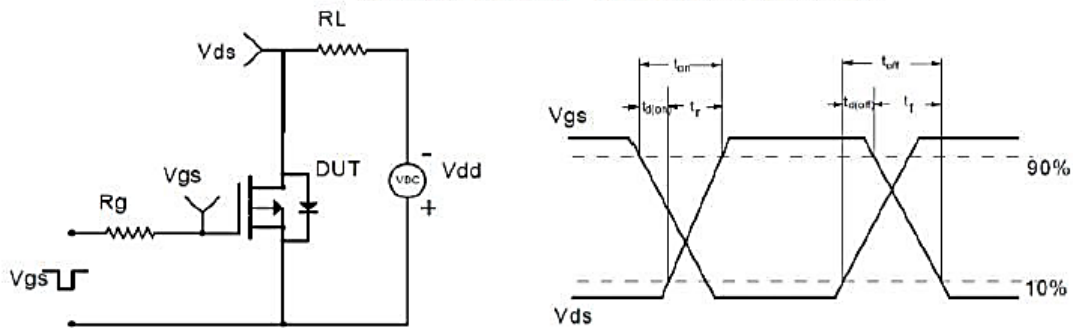


Test Circuit

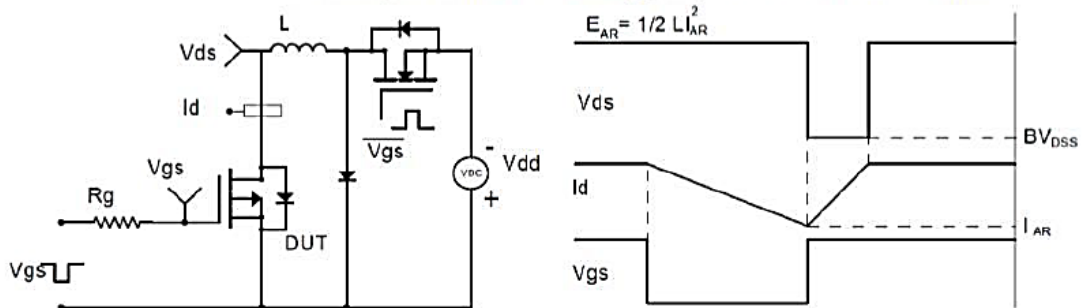
Gate Charge Test Circuit & Waveform



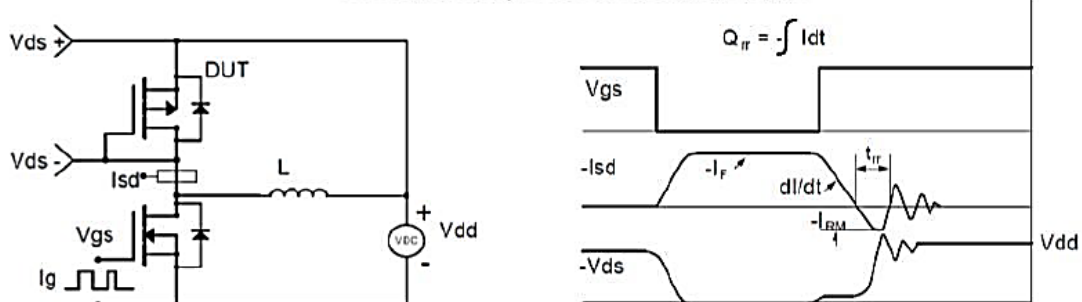
Resistive Switching Test Circuit & Waveforms



Unclamped Inductive Switching (UIS) Test Circuit & Waveforms

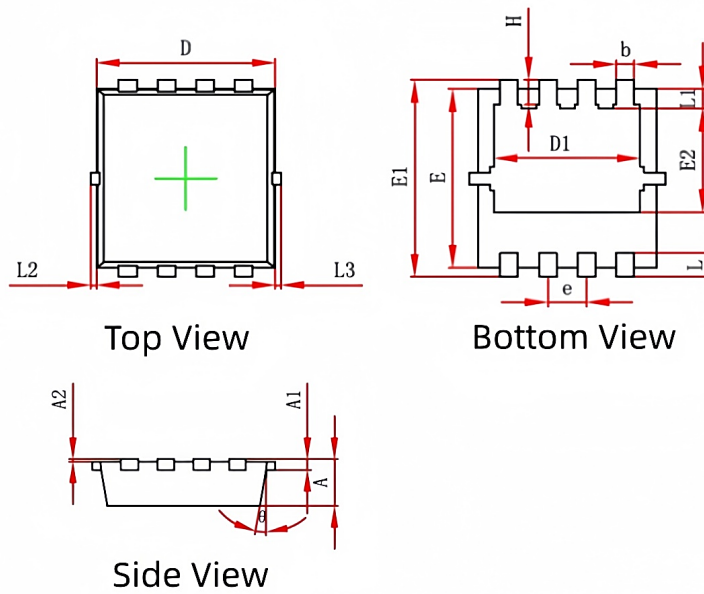


Diode Recovery Test Circuit & Waveforms

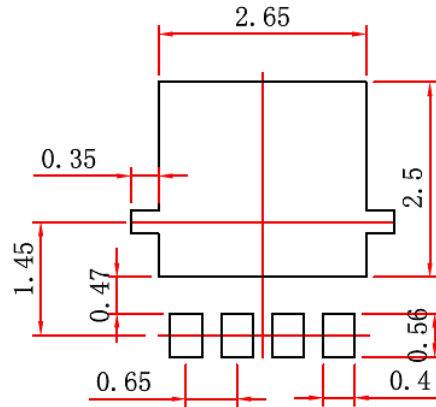




Package Mechanical Data(PDFN 3.3x3.3-8L)



| Symbol | Dimensions In Millimeters | | Dimensions In Inches | |
|----------|---------------------------|-------|----------------------|-------|
| | Min. | Max. | Min. | Max. |
| A | 0.650 | 0.850 | 0.026 | 0.033 |
| A1 | 0.152 REF. | | 0.006 REF. | |
| A2 | 0~0.05 | | 0~0.002 | |
| D | 2.900 | 3.100 | 0.114 | 0.122 |
| D1 | 2.300 | 2.600 | 0.091 | 0.102 |
| E | 2.900 | 3.100 | 0.114 | 0.122 |
| E1 | 3.150 | 3.450 | 0.124 | 0.136 |
| E2 | 1.535 | 1.935 | 0.060 | 0.076 |
| b | 0.200 | 0.400 | 0.008 | 0.016 |
| e | 0.550 | 0.750 | 0.022 | 0.030 |
| L | 0.300 | 0.500 | 0.012 | 0.020 |
| L1 | 0.180 | 0.480 | 0.007 | 0.019 |
| L2 | 0~0.100 | | 0~0.004 | |
| L3 | 0~0.100 | | 0~0.004 | |
| H | 0.315 | 0.515 | 0.012 | 0.020 |
| θ | 9° | 13° | 9° | 13° |



Note:

1. Controlling dimension: in millimeters.
2. General tolerance: $\pm 0.05\text{mm}$.
3. The pad layout is for reference purposes only.

Ordering information

| Order Code | Package | $V_{DS}(V)$ | $I_D(A)$ | $R_{DS(ON)}(m\Omega)$ | |
|-------------|------------|-------------|----------|-----------------------|----------------|
| | | | | $V_{GS}=-4.5V$ | $V_{GS}=-2.5V$ |
| QNM20PD02AJ | PDFN 3x3-8 | -20 | -20 | $V_{GS}=-4.5V$ | 12.5 |
| | | | | $V_{GS}=-2.5V$ | 16.5 |